



Attorney Docket No: 0492611-0543/MIT9277 CON 1

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Seleznev, *et al* Examiner: Cooke  
Serial No.: 10/799,436 Art Unit: 1751  
Filing Date: March 12, 2004  
Title: VACUUM PROCESSING FOR FABRICATION OF  
SUPERCONDUCTING THIN FILMS FABRICATED BY METAL-  
ORGANIC PROCESSING

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on September 22, 2005.

  
Susan M. Dinsmore

Sir:

**OFFICE ACTION RESPONSE UNDER 37 C.F.R. § 1.111**

This **Response to Office Action** is filed in response to the Office Action mailed March 29, 2005, objecting to claims 133 and 168, and rejecting claims 117-170. The cited references are Solovyov, "Ex-situ Post-deposition Processing for Large Area  $Y_1Ba_2Cu_3O_7$  Films and Coated Tapes," *IEEE Transactions on Applied Superconductivity*, 11:2939-2942 (2001) ("Solovyov") and U.S. Patents Nos. 5,650,378 to Iijima ("Iijima") and 6,610,428 to Smith ("Smith"). The following amendments and remarks remove all grounds for rejection of the application, thereby placing it in condition for allowance.

**Amendments to the Claims** are reflected in the listing of claims that begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.